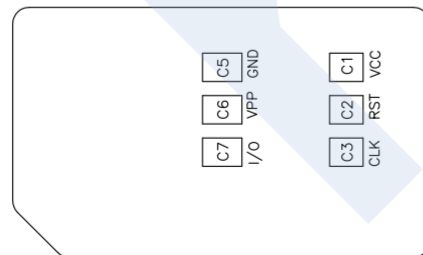
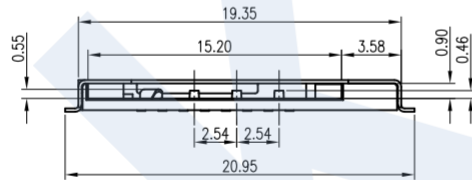
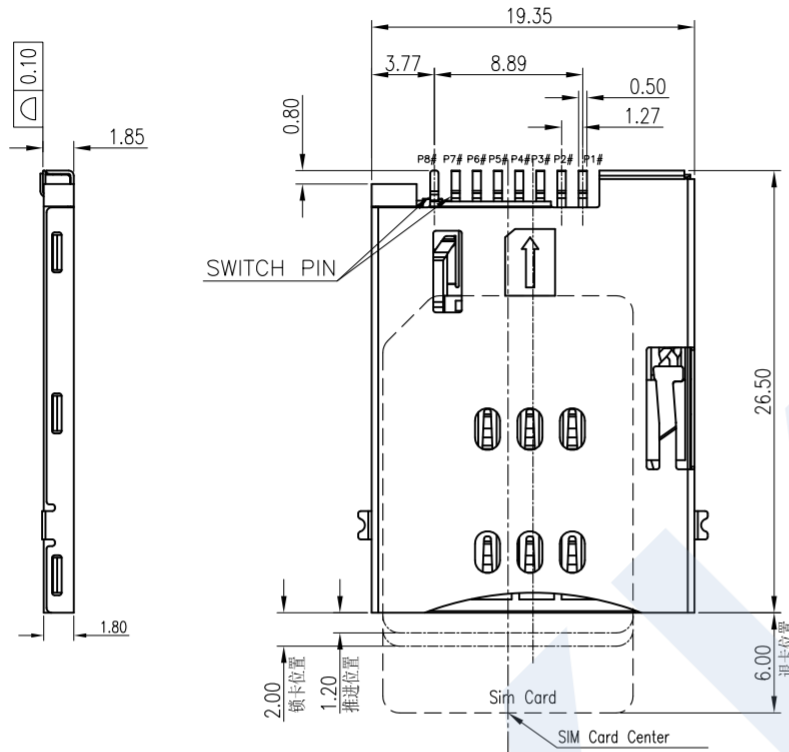
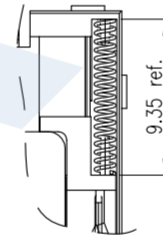
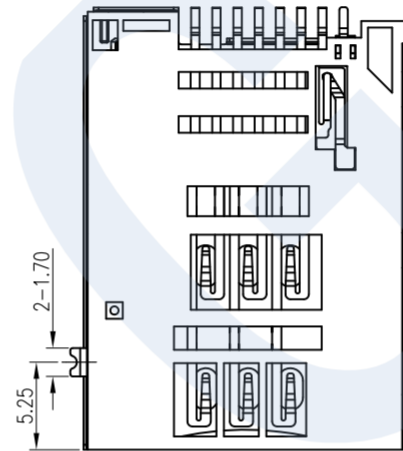


REV.	ECN	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A		NEW RELEASE	2016.03.09			

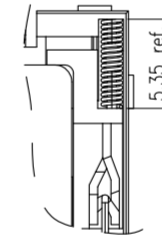


PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET

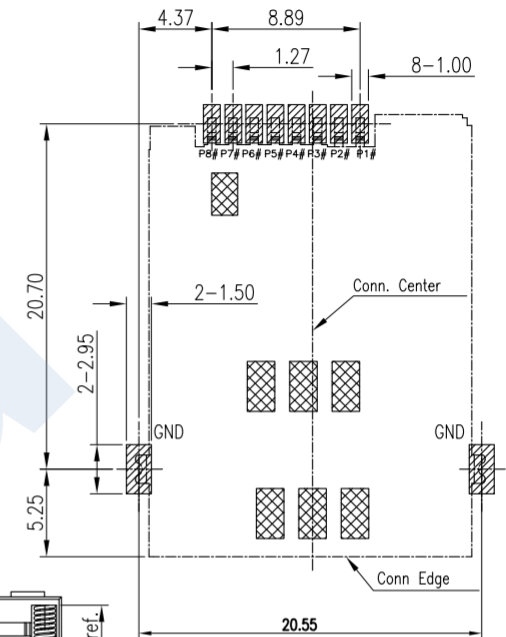
NOTES:  
 1) MATERIAL:  
 HOUSING: HIGH TEMPERATURE THERMOPLASTIC  
 CONTACT: COPPER ALLOY  
 SHELL: STEEL  
 2) FINISH:  
 CONTACT: GOLD FLASH PLATED ON CONTACT AREA;  
 MATTE-TIN PLATED ON SOLDER TAILS; WITH  
 ENTIRE CONTACT UNDERPLATED NICKEL.  
 SHELL: GOLD FLASH PLATED ON SOLDER TAILS  
 3) INFRARED REFLOW SOLDERING: 10sec. Min. at 260±10



预压状态



工作状态



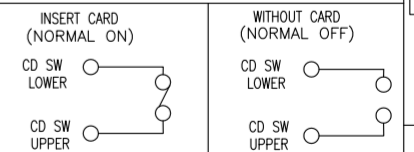
RECOMMENDED PCB LAYOUT(TOP VIEW)


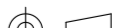
GENERAL TOLERANCES: ±0.05

⊠ SOLDER AREA

⊠ NONE CIRCUIT DIAGRAM AREA

Circuit Diagram for Card Detect Switch



MILLIMETERS	INCH	UNITS				
X° ± 2'	X° ± 2'	MM				
.X ± 0.30	.XX ± 0.012	MAT'L				
.XX ± 0.20	.XXX ± 0.008	SEE NOTES				
.XXX ± 0.10	.XXXX ± 0.004	FINISH				
		SEE NOTES	PART NUMBER:	TITLE: SIM card 6+2 pin push H1.8 (无定位柱)		
		QTY	APPD: Sean	DWG NO.:		
		SEE NOTES	CHKD:			
		DR: Yang				
				SCALE	SHEET	REV.
				1:1	1	A